

What the invention claimed is:

1. A connector terminal device fabrication method comprising the steps of:

(1) hole drilling, where a substrate is prepared and drilled,
5 forming a plurality of holes in said substrate;

(2) copper foil overlaying, where at least one copper foil is overlaid on said substrate; and

(3) etching, where said at least one copper foil is etched, forming contact spring arms in said holes and circuit lines
10 respectively extended from said contact spring arms.

2. The connector terminal device fabrication method as claimed in claim 1, wherein said at least one copper foil is electroplated, forming a circuit in said substrate.

3. The connector terminal device fabrication method as
15 claimed in claim 1, wherein said contact spring arms are suspended from said substrate for the contact of electronic member means.

4. The connector terminal device fabrication method as claimed in claim 3, wherein said electronic member is a circuit board.

20 5. The connector terminal device fabrication method as claimed in claim 1, wherein said at least one copper foil is respectively overlaid on top and bottom surfaces of said substrate during step (2) copper foil overlaying.

6. The connector terminal device fabrication method as claimed in claim 1, wherein said holes are blind holes.

7. A connector terminal device fabrication method comprising the steps of:

5 (1) hole drilling, where a substrate is prepared and drilled, forming a plurality of holes in said substrate;

(2) copper foil overlaying, where copper foils are respectively overlaid on the surfaces of said holes in said substrate; and

10 (3) etching, where said copper foils are etched, forming contact spring arms and circuit lines respectively electrically connected in said holes.

8. The connector terminal device fabrication method as claimed in claim 7, wherein said copper foils are electroplated,
15 forming a circuit in said substrate.

9. The connector terminal device fabrication method as claimed in claim 7, wherein said contact spring arms are suspended from said substrate for the contact of electronic member means.

10. The connector terminal device fabrication method as
20 claimed in claim 9, wherein said electronic member is a circuit board.

11. The connector terminal device fabrication method as claimed in claim 7, wherein said copper foils are respectively

partially overlaid on top and bottom surfaces of said substrate during step (2) copper foil overlaying, and etched during step (3) etching to form said contact spring arms at top and bottom sides of said substrate.

5 12. A connector terminal device formed of a substrate and at least one copper foil, wherein:

 said substrate comprises a plurality of through holes;

 said at least one copper foil is respectively located on at least one surface of said substrate, forming a plurality of contact
10 spring arms corresponding to said through holes and a plurality of circuit lines respectively extended from said contact spring arms for the contact of at least one electronic member.

 13. The connector terminal device as claimed in claim 12, wherein said circuit lines are respectively formed integral with said
15 contact spring arms.

 14. The connector terminal device as claimed in claim 12, wherein said at least one copper foil is respectively overlaid on top and bottom surfaces of said substrate.

 15. The connector terminal device as claimed in claim 12,
20 wherein said at least one copper foil is respectively overlaid on surfaces of said through holes.

 16. The connector terminal device as claimed in claim 15, wherein said contact spring arms are respectively suspended in top

and bottom sides of said substrate.

17. The connector terminal device as claimed in claim 12, wherein said contact spring arms and said circuit lines are adapted to accommodate a circuit board.

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